Application No. 10/026,125

Atty Docket No. MXIC 1517-1



In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

 (original) A method of relieving charge accumulations from non-volatile memory structures on dies on a wafer, including:

applying an electrical erase signal to the non-volatile memory structures on the dies: and

baking the wafer under conditions sufficient to diffuse charges resulting from the erase signal.

- (currently amended) The method of claim 1, wherein the electrical erase signal produces a negative gate channel erase by Fewler-Norheim Fowler-Nordheim tunneling.
- (currently amended) The method of claim 1, wherein the electrical erase signal produces a negative gate source side erase by Fowler-Norheim Fowler-Nordheim tunneling.
- (original) The method of claim 1, wherein the electrical erase signal produces a hot hole erase.
- (original) The method of claim 4, wherein the hot hole erase includes biasing either a source or drain of the memory cells.
- (original) The method of claim 4, wherein the hot hole erase includes biasing both of a source and drain of the non-volatile memory cells.
- (original) The method of claim 1, wherein the non-volatile memory structures include an ONO structure.



- 8. (original) The method of claim 7, wherein the electrical erase signal produces a hot hole erase.
- (original) The method of claim 8, wherein the hot hole erase includes biasing either a source or a drain of the memory cells.
- 10. (original) The method of claim 8, wherein the hot hole erase includes biasing both a source and a drain of the non-volatile memory cells.
- 11. (original) The method of claim 1, wherein the baking includes heating the wafer to between 80 and 150 degrees Celsius.
- 12. (original) The method of claim 1, wherein the baking includes heating the wafer to between 150 and 250 degrees Celsius.
- 13. (original) The method of claim 1, further including determining an erasure state of the memory cells and repeatedly applying an additional electrical erase signal until a predetermined erasure state is achieved.
- 14. (currently amended) A method of relieving charge accumulations from ONO non-volatile memory structures on dies on a wafer, including applying an electrical erase signal to the ONO non-volatile memory structures on the dies prior to subdividing the wafer into the dies, <u>further including baking the wafer after applying the electrical erase signal under conditions sufficient to diffuse charges resulting from the electrical erase signal.</u>
- 15. (cancelled) The method of claim 14, further including baking the wafer after applying the electrical erase signal under conditions sufficient to diffuse charges resulting from the electrical erase signal.
- (currently amended) The method of claim [[15]] 14, wherein the baking includes heating the wafer to between 80 and 150 degrees Celsius.

Application No. 10/026,125

Atty Docket No. MXIC 1517-1



- 17. (currently amended) The method of claim [[15]] 14, wherein the baking includes heating the wafer to between 150 and 250 degrees Celsius.
- 18. (currently amended) The method of claim 14, wherein the electrical erase signal produces a negative gate channel erase by Fowler-Norheim Fowler-Nordheim tunneling.
- 19. (currently amended) The method of claim 14, wherein the electrical erase signal produces a negative gate source side erase by Fowler-Northeim Fowler-Nordheim tunnelina.
- 20. (original) The method of claim 14, wherein the electrical erase signal produces a hot hole erase.
- 21. (original) The method of claim 20, wherein the hot hole erase includes biasing either a source or a drain of the memory cells.
- 22. (original) The method of claim 20, wherein the hot hole erase includes biasing both a source and a drain of the non-volatile memory cells.
- 23. (original) The method of claim 22, further including determining an erasure state of the memory cells and repeatedly applying an additional electrical erase signal until a predetermined erasure state is achieved.